

Silicone Adhesion Promoter

SK-AP02

Product Features:

- Enhances adhesion of addition-cure silicone to PPA, PET, PCBA, silver-plated surfaces, and other substrates.
- Hydrogen-reactive formulation.
- Minimal impact on inorganic filler system viscosity; low thixotropy.

Technical Specifications:

Parameter	Typical Data	Test Standard
Appearance	Colorless to pale yellow transparent liquid	Visual inspection
Kinematic viscosity (mm ² /s @25°C)	10–100	GB/T 10247-2008
Refractive index (25°C)	1.44 – 1.46	GB/T 6488
Hydrogen content (wt%)	0.2–0.36	HG/T 4804-2015

Typical Applications:

- Selective adhesion promoter for functional thermal-conductive/ flame-retardant potting compounds.
- Substrate anchoring for addition-cure pressure-sensitive adhesives.
- Adhesion enhancement in low/high-power LED encapsulation silicones.

Usage Guidelines:

- Add to the hydrogen-containing component at 1–2% by weight.
- Recommended curing temperature: above 100°C (curing time varies by application).

Packaging & Storage:

- Available in 5KG pails or 20KG cartons.
- Store at 0–8°C for optimal stability. Short-term room-temperature storage (<1 month) is acceptable but not advised.
- Non-flammable and non-explosive; classified as non-hazardous for transport.
- Best used within 3 months of production. Re-testing required if expired.

Safety & Environmental:

- Wear appropriate protective equipment when handling. Refer to the Material Safety Data Sheet (MSDS) for details.
- Dispose of packaging per local solid waste regulations.

Notes:

- The information provided in this document is based on reliable data from our company. Product specifications and performance may change without prior notice.
- The information is derived from laboratory and practical experience and is for reference only. Since conditions and methods of use are beyond our control, application testing is recommended before use.
- Some performance parameters of the product can be adjusted according to customer requirements. If needed, please contact our technical department engineers.